



SUPER FAST GLASS PASSIVATED RECTIFIERS

Reverse Voltage – 100 to 600 V

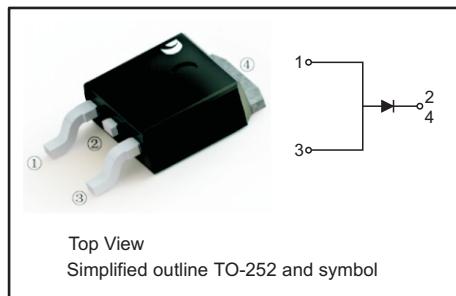
Forward Current – 10 A

FEATURES

- High current capability
- Low forward voltage drop
- Low power loss, high efficiency
- High surge capability
- High temperature soldering guaranteed

PINNING

PIN	DESCRIPTION
2,4	Cathode
1,3	Anode



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

Parameter	Symbols	SF1001DYC	SF1002DYC	SF1003DYC	SF1004DYC	SF1005DYC	SF1006DYC	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	300	400	500	600	V
Maximum RMS voltage	V_{RMS}	70	140	210	280	350	420	V
Maximum DC Blocking Voltage	V_{DC}	100	200	300	400	500	600	V
Maximum Average Forward Rectified Current @ Fig.1	$I_{F(AV)}$	10						A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	170						A
Peak Forward Surge Current, 1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	340						A
I^2t Rating for fusing (3ms $\leq t \leq$ 8.3ms)	I^2t	119.9						A^2s
Max Instantaneous Forward Voltage at 10 A	V_F	1		1.3		1.7		V
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Reverse Voltage $T_a = 125^\circ C$	I_R	1 350						μA
Typical Junction Capacitance ⁽¹⁾	C_j	189		123		80		pF
Maximum Reverse Recovery Time ⁽²⁾	t_{rr}	35						ns
Typical Thermal Resistance ⁽³⁾	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	55 6 10						$^\circ C/W$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ C$

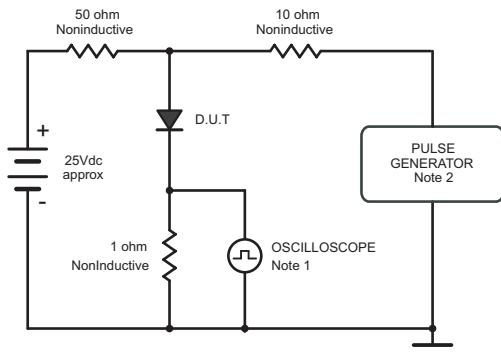
(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C.

(2) Measured with $I_F = 0.5 A$, $I_R = 1 A$, $I_{rr} = 0.25 A$.

(3) P.C.B. mounted with 0.3" X 0.3" (8mm X 8mm) copper pad areas.



Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.

Fig.1 Forward Current Derating Curve

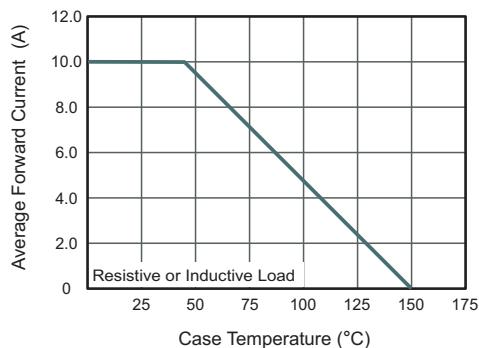


Fig.3 Typical Forward Characteristics

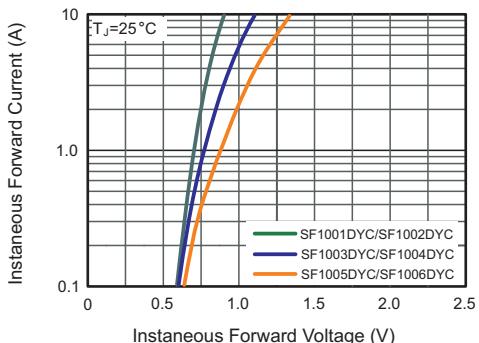


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

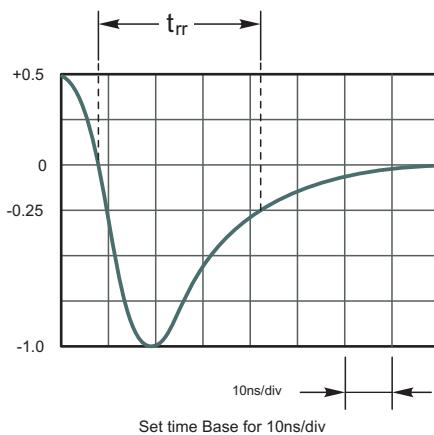
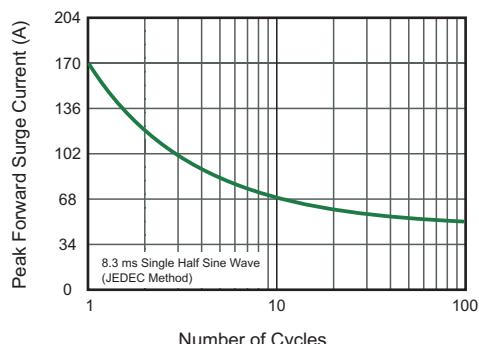


Fig.2 Typical Reverse Characteristics

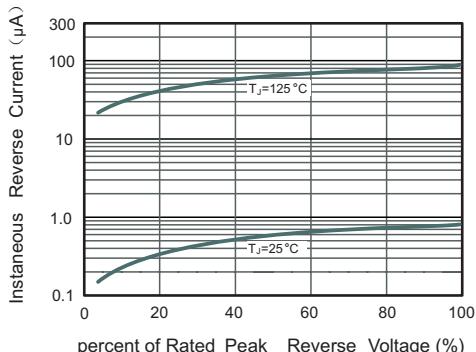
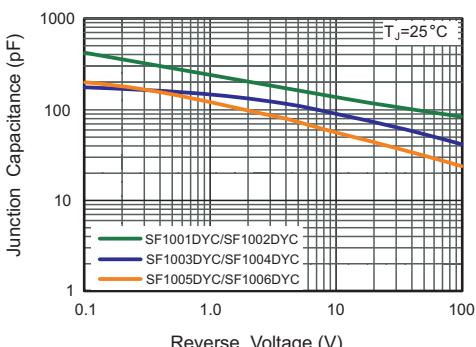


Fig.4 Typical Junction Capacitance

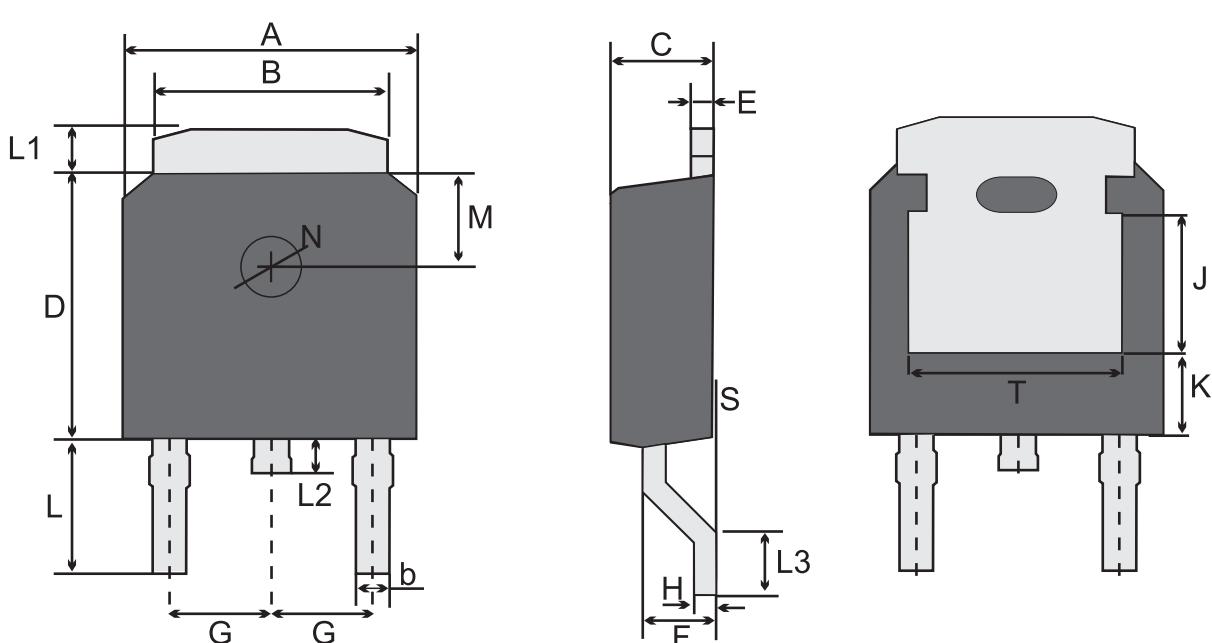




PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

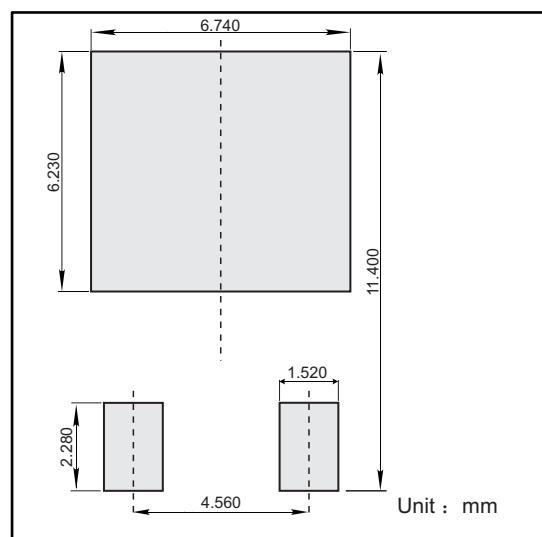
TO-252



TO-252(D-PAK) mechanical data

UNIT	A	B	b	C	D	E	F	G	H	L	L1	L2	L3	S	M	N	J	K	T	
mm	max	6.7	5.5	0.86	2.5	6.3	0.6	1.8	2.29 TYPICAL	0.55	3.1	1.2	1.0	1.75	0.1	1.8 TYPICAL	1.3 TYPICAL	3.16 ref.	1.80 ref.	4.83 ref.
	min	6.3	5.1	0.66	2.1	5.9	0.4	1.3		0.45	2.7	0.8	0.6	1.40	0.0					
mil	max	264	217	34	98	248	24	71	90 TYPICAL	22	122	47	39	69	4	71 TYPICAL	51 TYPICAL	124 ref.	71 ref.	190 ref.
	min	248	201	26	83	232	16	51		18	106	31	24	55	0					

The recommended mounting pad size



Marking

Type number	Marking code
SF1001DYC	SF1001DY
SF1002DYC	SF1002DY
SF1003DYC	SF1003DY
SF1004DYC	SF1004DY
SF1005DYC	SF1005DY
SF1006DYC	SF1006DY



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